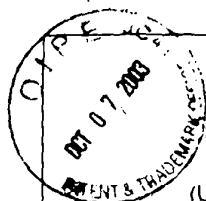


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Attorney Docket No. 108298633US

Disclosure No. 01-0389


**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

 Form PTO-1449 (Modified)
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COMPLETE IF KNOWN

Application Number	10/034,924
Confirmation Number	1417
Filing Date	December 26, 2001
First Named Inventor	Stephen Moxham
Group Art Unit	2826
Examiner Name	Alexander O. Williams
Attorney Docket No.	108298633US

Sheet 1 of 2

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11/17/03

*EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application(s).



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Sheet 2 of 2

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